

**ABSTRACT OF THE DISCLOSURE**

The surface mount flipchip capacitor of the present invention includes a wire and a conductive powder element electrically connected to the wire. The surface mount flipchip capacitor has insulative material surrounding at least a portion of the conductive powder element and the wire extending below the conductive powder element. A first terminal is formed on the surface mount flipchip capacitor at the first end surface of the wire and a second terminal is formed by being electrically connected to the conductive powder element. The surface mount flipchip capacitor of the present invention is created by methods which include the steps of providing a wire and placing conductive powder upon the wire. One embodiment of the present invention creates multiple wires from a foil sheet and electrophoretically deposits conductive powder element upon the wire.